

Appl. No. 10/762,122
Amdt. dated July 1, 2005
Reply to Office action of May 4, 2005

Amendment to the Specification

Please replace the Abstract currently on file with the Abstract below:

ABSTRACT

A leadframe for use with integrated circuit chips comprising a base metal having a plated layer of nickel fully covering the base metal; a plated layer of pure tin on the nickel layer, selectively covering areas of the leadframe intended for attachment to other parts; and a plated layer of palladium on said nickel layer, selectively covering areas of said Leadframe intended for bonding wire attachment.